



SPECIFICATION

• Supplier : Samsung electro-mechanics • Samsung P/N : CL32B105KCJSNNE

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 1µF, 100V, ±10%, X7R, 1210

A. Samsung Part Number

<u>CL</u> <u>32</u> <u>B</u> <u>105</u> <u>K</u> <u>C</u> <u>J</u> <u>S</u> <u>N</u> <u>N</u> <u>E</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor								
2	Size	1210 (ind	ch code)	L:	3.2	± 0.3	mm	W:	2.5 ± 0.2	mm
3	Dielectric	X7R			(8)	Inner e	electrode	١	J i	
4		1 µF			_	Termir		(Cu/Ag-Epoxy	
⑤	Capacitance	±10 %				Plating	9	5	Sn 100%	(Pb Free)
	tolerance				9	Produ	ct	١	Normal	
6	Rated Voltage	100 V			10	Specia	al	F	Reserved for	future use
7	Thickness	2.5 ± 0	.2 mm		11)	Packa	ging	Е	Embossed Ty	pe, 7" reel

B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition				
Capacitance	Within specified tolerance	1klb±10%				
Tan δ (DF)	0.025 max.					
Insulation	10,000Mohm or 500Mohm⋅μF	Rated Voltage 60~120 sec.				
Resistance	Whichever is Smaller					
Appearance	No abnormal exterior appearance	Microscope (×10)				
Withstanding	No dielectric breakdown or	200% of the rated voltage				
Voltage	mechanical breakdown					
Temperature	X7R					
Characterisitcs	(From -55 ℃ to 125 ℃, Capacitance change shoud be within ±15%)					
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.				
of Termination	terminal electrode					
Bending Strength	Capacitance change : within ±12.5%	Bending to the limit (1mm)				
		with 1.0mm/sec.				
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder				
	is to be soldered newly	245±5℃, 3±0.3sec.				
		(preheating : 80~120℃ for 10~30sec.)				
Resistance to	Capacitance change: within ±7.5%	Solder pot : 270±5℃, 10±1sec.				
Soldering heat	Tan δ, IR : initial spec.					

	Performance	Test condition
Vibration Test	Capacitance change : within ±5%	Amplitude : 1.5mm
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)
		2hours × 3 direction (x, y, z)
Moisture	Capacitance change : within ±12.5%	With rated voltage
Resistance	Tan δ: 0.05 max	40±2℃, 90~95%RH, 500+12/-0hrs
	IR : 500Mohm or 25Mohm · μΓ	
	Whichever is Smaller	
High Temperature	Capacitance change : within ±12.5%	With 200% of the rated voltage
Resistance	Tan δ : 0.05 max	Max. operating temperature
	IR : 1000Mohm or 50Mohm · μF	
	Whichever is Smaller	1000+48/-0hrs
Temperature	Capacitance change : within ±7.5%	1 cycle condition
Cycling	Tan δ, IR : initial spec.	Min. operating temperature → 25°C
		$ ightarrow$ Max. operating temperature $ ightarrow$ 25 $^{\circ}\!$
		5 cycle test

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^{\circ}$ C , 10sec. Max)

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.